

PROCESS OF CONTROLLING GRAIN GROWTH IN METAL FILM

ABSTRACT

A process for controlling grain growth in the microstructure of thin metal films (e.g., copper or gold) deposited onto a substrate. In one embodiment, the plated film is stored, after the step of depositing, at a temperature not greater than -20°C , wherein the fine-grained microstructure is stabilized without grain growth for the entire storage period.

FIG.3